L Number	Hits	Search Text	DB	Time stamp
1	5148	(257/211,266,324,635,700,758).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 13:52
2	6124	(438/118,128,129,216,261,591,593,622).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 13:53
4	0	((438/118,128,129,216,261,591,593,622).CCLS.) and 'multiple-chip'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 13:54
3	4	((257/211,266,324,635,700,758).CCLS.) and 'multiple-chip'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 13:55
5	10890	multiple-chip multi near chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 13:55
6	245	multiple-chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 14:12
7	7	(first adj chip and second adj chip) with circuit near surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 13:58
8	5855	first adj wiring and second adj wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 13:58
9	481	(first adj wiring and second adj wiring) with semiconductor adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 14:00
10	0	(((firs tadj chip) near3 surface) and ((second adj chip) near3 surface)) with confront$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 14:03
11	4	(("6402463") or ("6429528")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 14:04
12	2	("6403463").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 14:06

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13	1	09/956973	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 14:07
14	4	((257/211,266,324,635,700,758).CCLS.) and multiple-chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 14:13
15	49	multiple-chip and Stack$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 14:26
16	1	(multiple-chip and Stack$4) and lsi	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 14:26
17	23	(multiple-chip and Stack$4) and bus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/08 14:27

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